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Su		02512749 ney Docket No.: 0074/032	00
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	Additional name(s) attached? □ Yes ■ No	Additional names/addresses attached? □ Yes ■ No	
3.	Nature of conveyance: Assignment Merger Security Agreement Change of Name Other:		
	Execution Date: June 27, 2003		
4.	Application number(s) or patent number(s): 10/408,670 If this document is being filed with a new application, t A. Patent Application No.(s): 10/408,676		
	Additional numbers attached? □ Yes ■ I	No	
5.	Name/address of party to whom correspondence concerning document should be mailed:	6. Total number of applications/patents involved:	1
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PATENT REEL: 014323 FRAME: 0245

## ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned.

(1)	Mitsukazu KUZE	(6)
(2)	Hiroyuki TAKEWA	(7)
(3)	Mikio IWASA	(8)
(4)		(9)
(5)		(10)

who has/have made a certain new and useful invention, hereby sell, assign and transfer unto

## Matsushita Electric Industrial Co., Ltd.

1006, Oaza-kadoma, Kadoma City, Osaka Pref., 571-8501 Japan

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

## SURROUNDING STRUCTURE OF A LOUDSPEAKER

(a) for which an application for United States Letters Patent was filed on <u>April 8, 2003</u>, and identified by United States Serial No. 10/408,676 ; or

(b) for which an application for United States Letters Patent was executed on

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE:

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date(s) indicated aside my/our signature(s):

DATE SIGNED INVENTOR (S) (1) <u>Mitsukazu Kuze</u> Name: Mitsukazu KUZE
 (2) <u>Airoyuki Takum</u> Name: Hiroyuki TAKEWA
 (3) <u>Mikio Uwasa</u> Name: Mikio IWASA June 27, 2003 June 27, 2003 June 27, 2003 (4)Name: (5) Name:

**RECORDED: 07/28/2003** 

PATENT REEL: 014323 FRAME: 0246